

Surface Mount Lowpass Filters

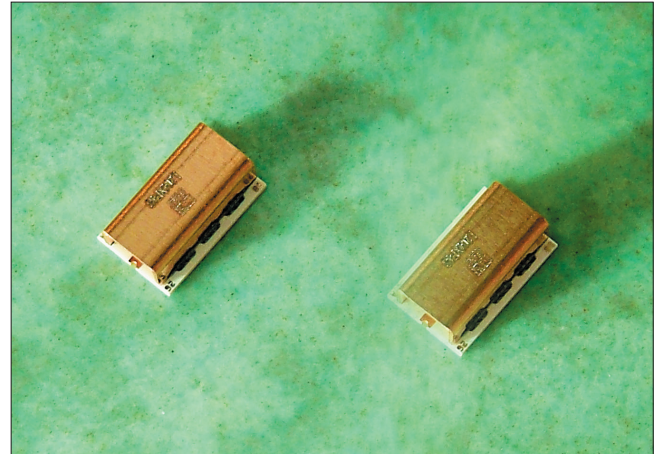
Part numbers L050XF9S to L254XF3S

Description

DLI introduces its new high frequency surface mountable catalog low pass filters. These LPF's incorporate DLI's low loss high permittivity ceramics which provide small size and temperature stability. The catalog LPF's are offered in a variety of frequency bands, which offers a drop in solution for high frequency attenuation.

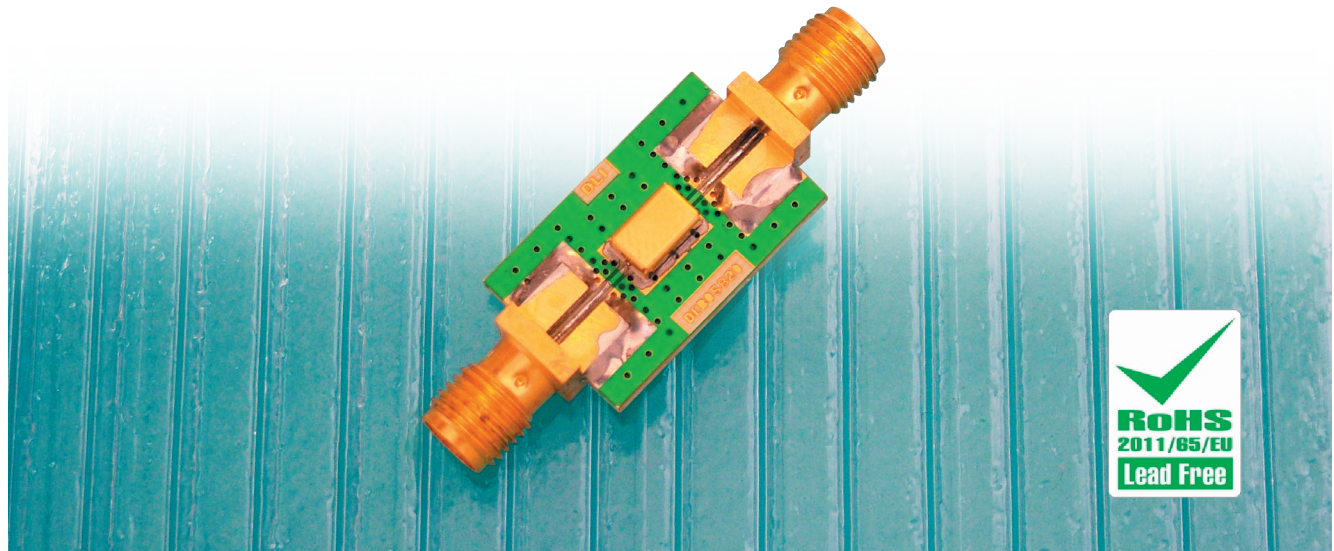
Features

- Small Size
- Fully Shielded Component
- Frequency Stable over Temperature
- Solder Surface Mountable
- Excellent Repeatability
- Operating Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω
- 100% Tested & Inspected



Specifications

Part Number	3 dB Cutoff	Passband	Max Insertion Loss in Passband	Min VSWR in Passband	Min Rejection	Length Inches (mm)	Width Inches (mm)	Height Inches (mm)
L050XF9S	5 GHz	DC - 4 GHz	1 dB	1.288:1	6 - 16 GHz (35dB)	0.220 (5.58)	0.180 (4.57)	0.103 (2.62)
L065XG9S	6.5 GHz	DC - 6 GHz	1.3 dB	1.22:1	7.9 - 22.4 GHz (35 dB)	0.220 (5.58)	0.180 (4.57)	0.103 (2.62)
L095XG9S	9.5 GHz	DC - 9 GHz	1.3 dB	1.12:1	11.5 - 32 GHz (30 dB)	0.220 (5.58)	0.140 (3.56)	0.103 (2.62)
L117XH4S	11.7 GHz	DC - 11 GHz	1 dB	1.43:1	17.6 - 30 GHz (40 dB)	0.220 (5.58)	0.140 (3.56)	0.103 (2.62)
L128XH4S	12.8 GHz	DC - 12 GHz	1.2 dB	1.38:1	18.8 - 32 GHz (40 dB)	0.220 (5.58)	0.140 (3.56)	0.103 (2.62)
L157XG3S	15.7 GHz	DC - 15 GHz	2.2 dB	1.3:1	19.9 - 32.2 GHz (40 dB)	0.220 (5.58)	0.140 (3.56)	0.103 (2.62)
L204XF4S	20.4 GHz	DC - 20 GHz	1.8 dB	1.43:1	23 - 43 GHz (30 dB)	0.220 (5.58)	0.140 (3.56)	0.098 (2.49)
L254XF3S	25.4 GHz	DC - 25 GHz	1.4 dB	1.3:1	29 - 50 GHz (30 dB)	0.220 (5.58)	0.140 (3.56)	0.098 (2.49)



Soldering Information

DLI solderable components are compatible with both SnPb and 100% Sn mounting methods. Unless otherwise specified, component termination metal is Ni/Au. Gold layer is less than 6 micro-inch to eliminate any Au embrittlement concern. A detailed application note is available at dilabs.com.

Use of Silver Loaded Epoxy Adhesives

Use of conductive epoxy in place of solders is not recommended on our solder surface mountable components. Isolation must be maintained between the ground plane and signal traces when mounted on PCB. Epoxy may bleed out and degrade performance.

Board Layout Design (SMT)

Board layout for each surface mountable device will require a ground plane with RF I/O traces. Each catalog part number may require a different PCB pattern recommendation and the individual datasheet and pattern recommendation should be reviewed. Devices are designed for a single ended 50 ohm system unless otherwise stated. Proper transmission line impedance is required to meet published electrical specifications.

Published test data of component on Rogers RO4350B® 10 mil thick material. Components were designed to work with other board materials when source impedance are matched to 50Ω. Please contact DLI Applications Engineering with any questions on use of other RF layer.

See dilabs.com for more detailed application note on board mounting recommendations.

RoHS

All products are RoHS compliant.

Chip and Wire Information

DLI wire bond devices are designed for silver loaded epoxy adhesives to ground plane. A wire bond to I/O pad with thermo compression ball or wedge bonding on MIL-STD gold thickness (min 50 micro-inch). Device is also compatible with standard die attach methods but not compatible with Sn or SnPb solderable methods. Follow typical microwave wire bonding practices to minimize added inductance that may adversely impact electrical performance.

Packaging

Components will be packaged in best standard commercial practices unless otherwise noted or requested. Packaging options include bulk and tape and reel.

Handling & Storage

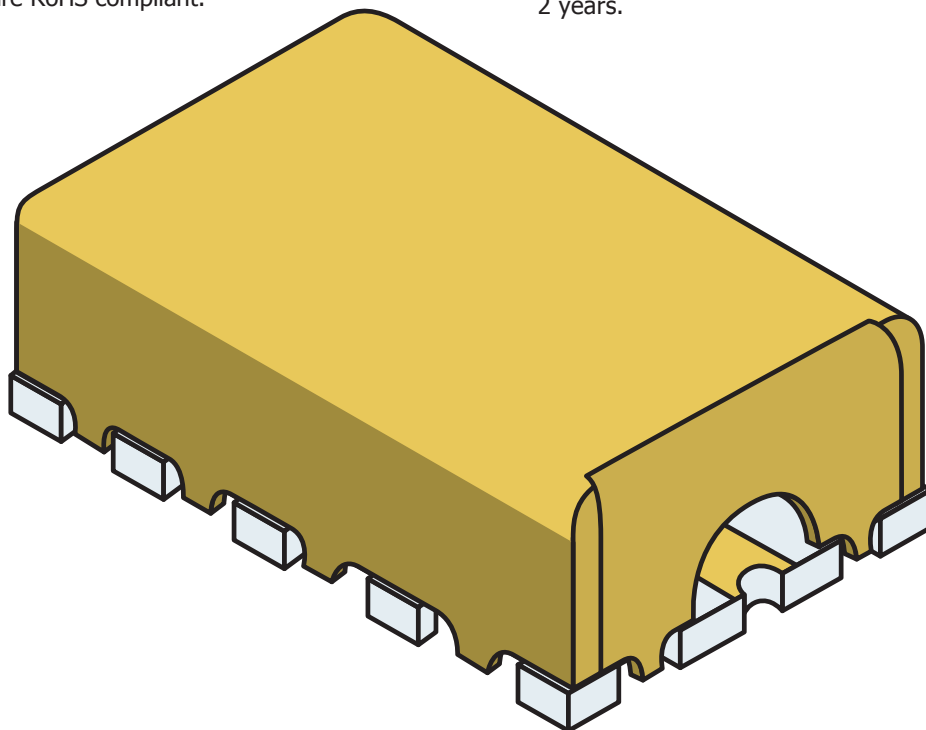
Components should never be handled with fingers; perspiration and skin oils can inhibit solderability or wire bond ability and will aggravate cleaning.

Ceramic components should never be handled with metallic instruments. Metal tweezers should never be used as these can chip the product and leave abraded metal tracks on the product surface. Plastic, carbon fiber and plastic coated metal types are readily available and recommended.

Devices are designed to withstand typical storage conditions. Devices may be stored between -55°C and +125°C and in a non-condensing environment.

Taped product should be stored out of direct sunlight, which might promote deterioration in tape performance.

Product, stored under the conditions recommended above, in its "as received" packaging, has a minimum shelf life of 2 years.



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